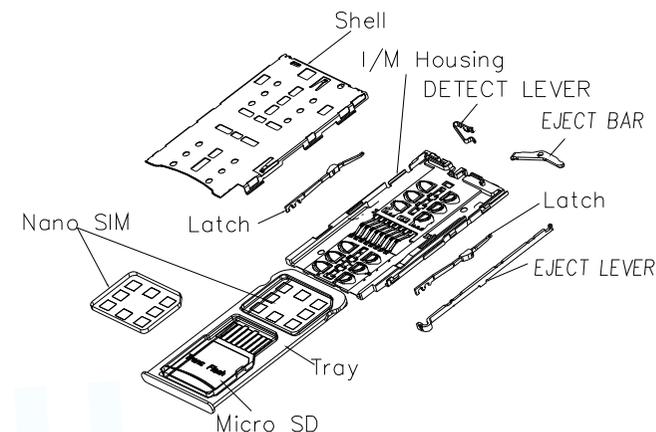
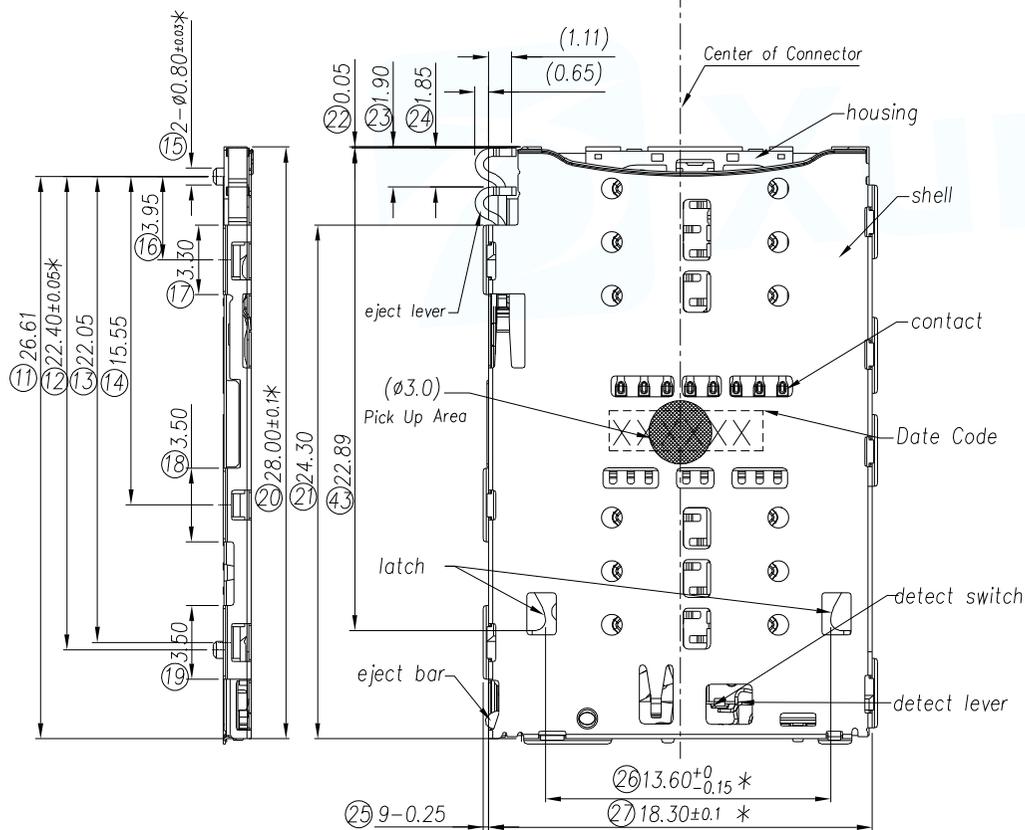
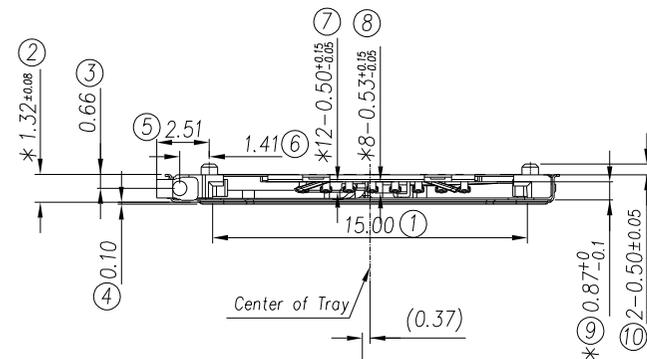


MAPX	MODIFICATION	DATE	DRAW	APPROVE

D/C Annotation

XX X X XX
 Date
 01,02,03.....
 Month
 A: Jan; B: Feb.....
 Year
 5: 2015; 6: 2016.....
 Line
 01,02,03.....



8	LATCH MOLD	PA9T UL94V-0	2	NO PLATING, BLACK PLASTIC
7	LATCH	SUS301-H T=0.30mm	2	NO PLATING
6	DETECT LEVER	C7035-TM06 T=0.15mm	1	3u" Au PLATING ON CONTACT AREA, 2u" Au PLATING ON SOLDER TAILS, 50u" Min. Ni UNDERPLATING OVER ALL
5	EJECT LEVER	SUS304-H T=0.40mm	1	NO PLATING
4	EJECT BAR	SUS304-1/2H T=0.40mm	1	NO PLATING
3	SHELL	SUS301-H T=0.10mm	1	2u" Au PLATING ON SOLDER TAILS, 50u" Min. Ni UNDERPLATING OVER ALL
2	CONTACT	C5240HQ-SH T=0.08mm	1	3u" Au PLATING ON CONTACT AREA, 2u" Au PLATING ON SOLDER TAILS, 50u" Min. Ni UNDERPLATING OVER ALL
1	HOUSING	LCP UL94 V-0	1	PURE MATERIAL, BLACK COLOR
ITEM	NAME	MATERIAL	Q'TY	REMARK

MANUFACTURE DWG



UNLESS OTHERWISE SPECIFIED TOLERANCES



TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD

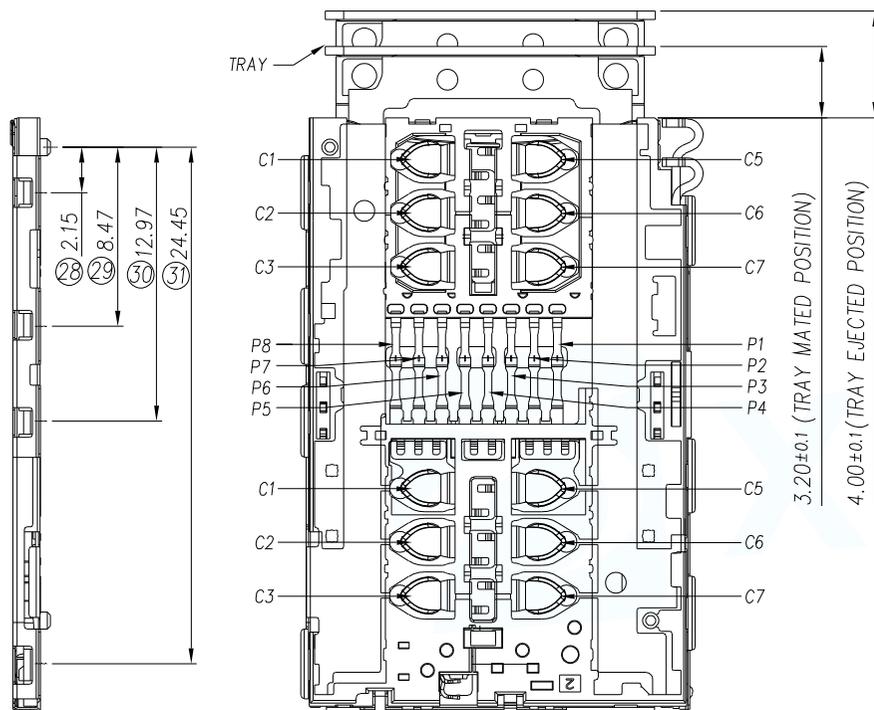
DECIMALS: ANGLES:

X.:±0.20 X'.:±2'

X.X:±0.15 .X':±1"

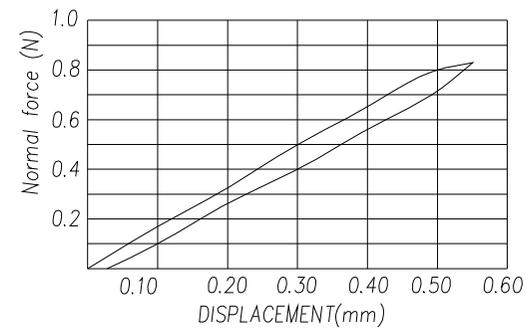
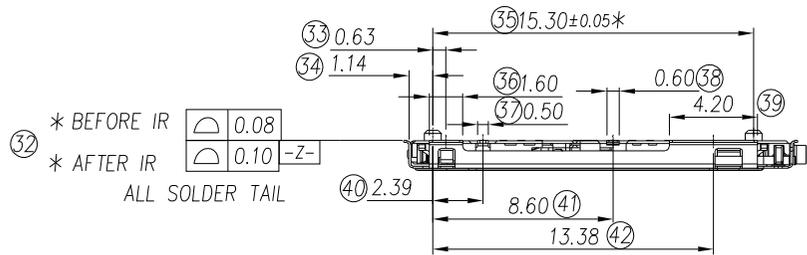
X.XX:±0.10

PAR	MCS-302S-C1
DWN	
CHKD	
APVD	
SCALE:1:1	UNIT:MM
SIZE:A4	SHEET:1F1
CUSTOMER COPY	REV:A

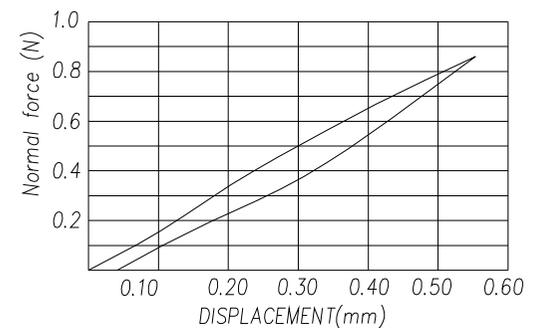


NOTES:

- PRODUCT SPECIFICATIONS:
 VOLTAGE RATING: 10V
 CURRENT RATING: 0.5A
 INSULATION RESISTANCE: 1000 MEG.OHM MIN
 CONTACT RESISTANCE: INITIAL 50mΩ Max; AFTER TEST R=30mΩ
 OPERATION TEMPERATURE: -25° TO +85°
 DURABILITY: 3000 CYCLES
 TRAY MATING FORCE: 2~10N; TRAY UNMATING FORCE: 4~10N
 OPERATING FORCE: 4~10N
 THE RESORPTION DISTANCE OF THE TRAY: 0.40mm MIN.

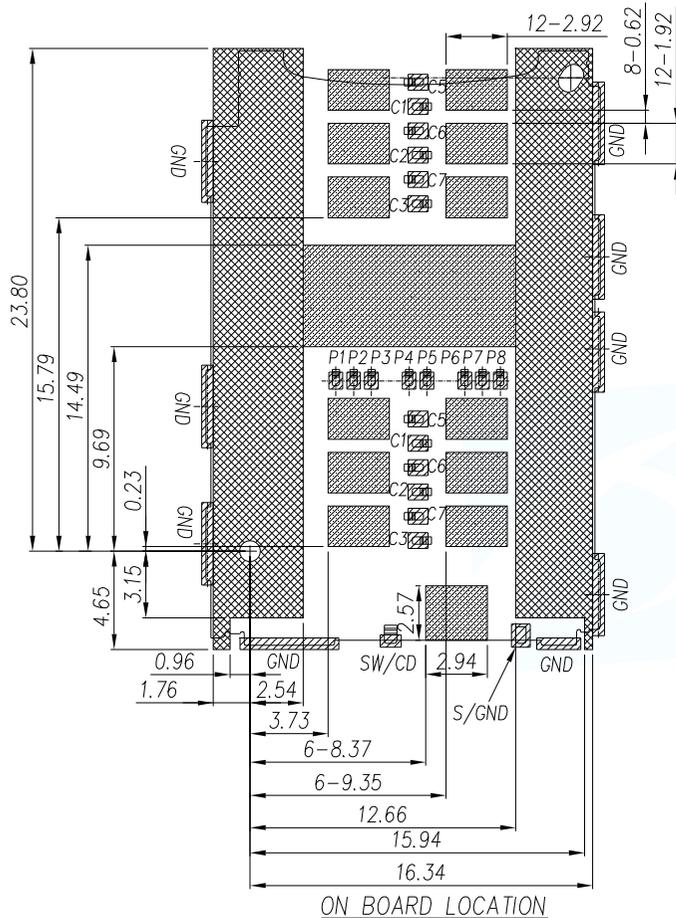


Nano Sim card Contact NF-Deflection Curve



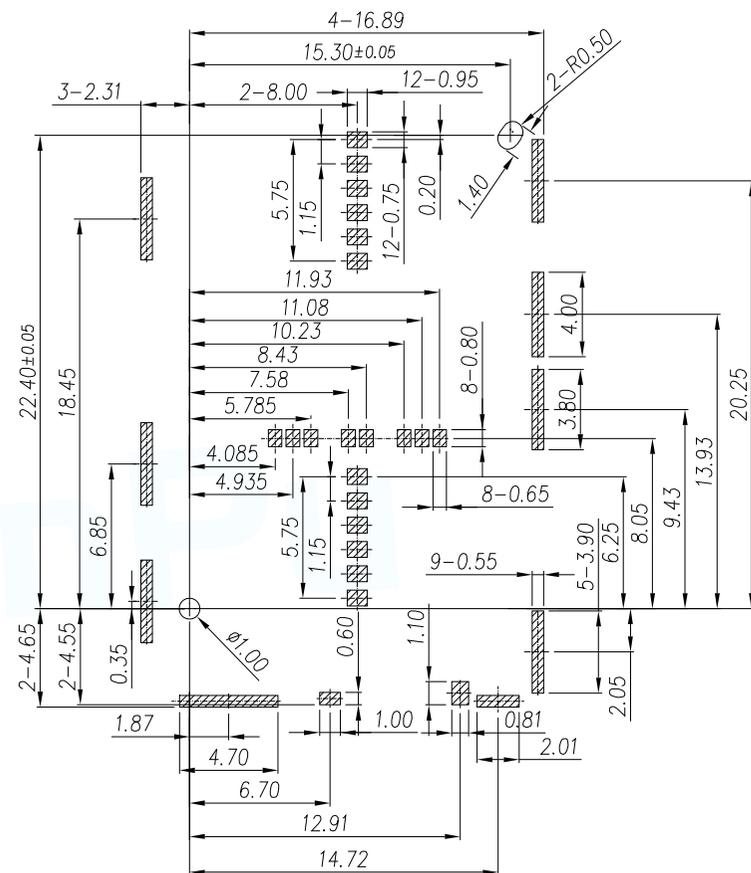
Micro SD Card Contact NF-Deflection Curve

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	MCS-302S-C1
DECIMALS:	ANGLES:	DWN		
X.:±0.20	X'.:±2°	CHKD		
X.X:±0.15	.X':±1°	APVD		
X.XX:±0.10		SCALE:1:1	UNIT:MM	
		CUSTOMER COPY	SIZE:A4	
			SHEET:1F1	
			REV:A	



ON BOARD LOCATION

- Through Hole
 - ▨ Soldering Pad Area
 - ▩ Open Wire Restricted Area
(Possibility Touch Of Components On PCB)
 - ▧ No Soldering Pad Area(Independent Pad Area)
OR Open Wire&Copper Restricted Area
- 1: Touch area of contact tips, No electrical function and only for mechanical func
2: No first PCB-Layout circuits in the area.

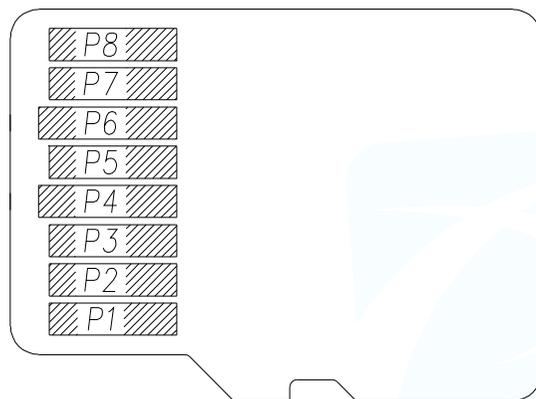
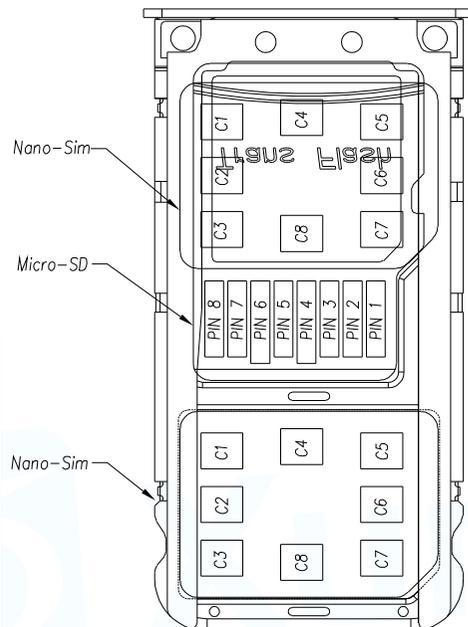


PCB LAYOUT TOLERANCE: ±0.05
METAL MASK THICKNESS: 0.10MM

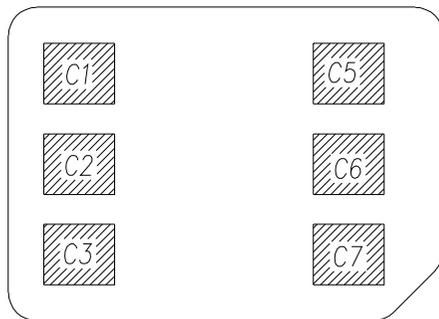
MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	MCS-302S-C1
DECIMALS:	ANGLES:	DWN		
X.:±0.20	X'.:±2°	CHKD		
X.X:±0.15	.X':±1°	APVD		
X.XX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		CUSTOMER COPY	REV:A	



BOTTOM VIEW

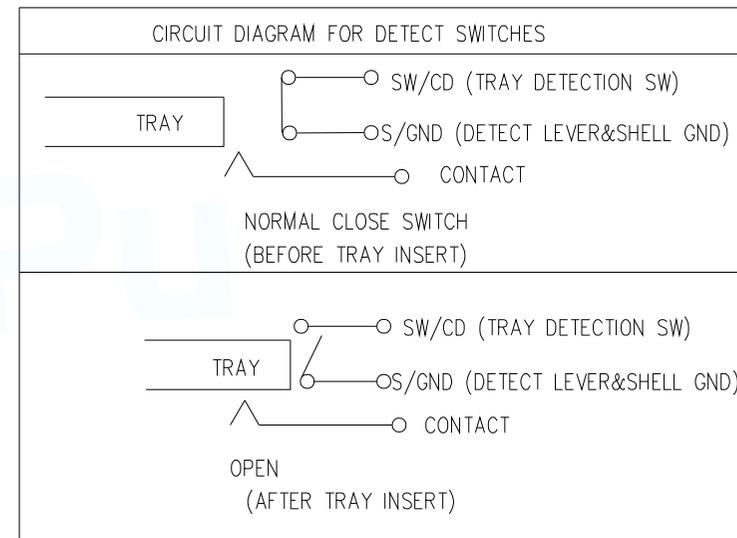


Micro SD CARD ELECTRICAL

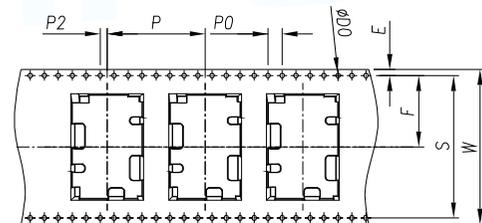
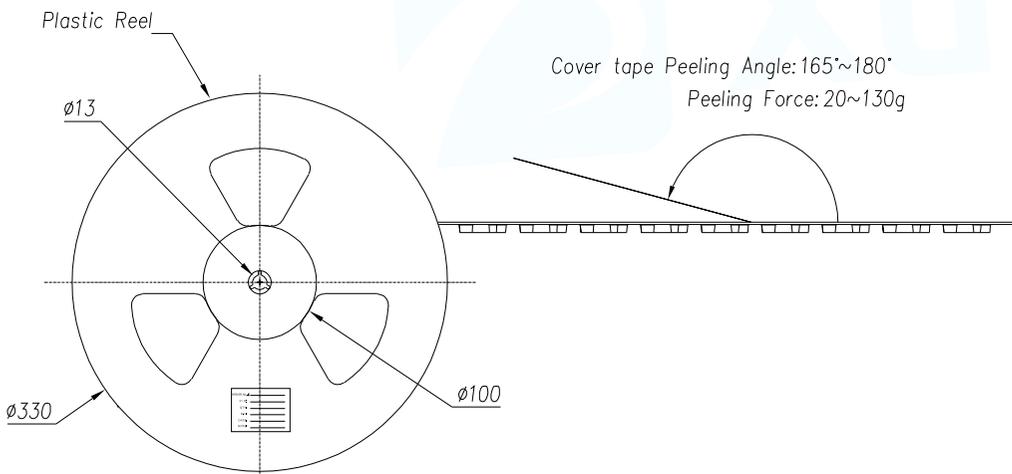
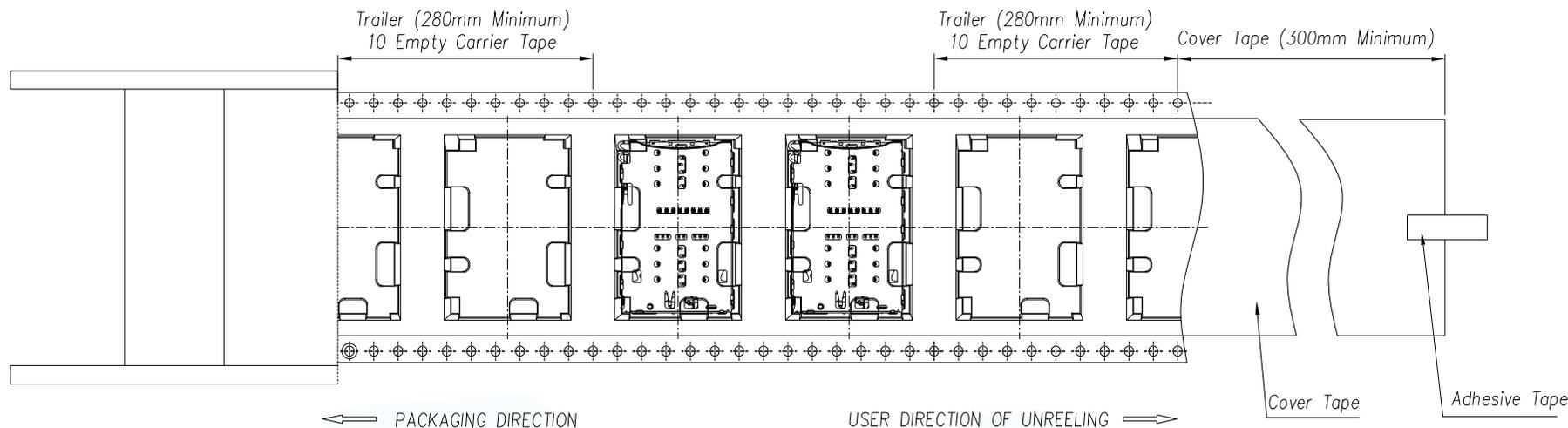


NANO SIM CARD ELECTRICAL

ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM



MANUFACTURE DWG		<p>东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd</p>	TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	MCS-302S-C1
DECIMALS:	ANGLES:	DWN		
X.:±0.20	X'.:±2'	CHKD		
X.X:±0.15	.X':±1'	APVD		
X.XX:±0.10		SCALE1:1	UNIT:MM	
		CUSTOMER COPY	SIZE:A4	
			SHEET:1F1	
			REV:A	



P	28.00±0.10
P0	4.00±0.10
P2	2.00±0.10
D0	1.50±0.10
E	1.75±0.10
F	20.20±0.10
S	40.40±0.10
W	44.00±0.10

1	MCS-302L-C1	800	6	9.95	4800	340X340X335
ITEM	PRODUCT NO:	QTY/REEL	REEL/CARTON	Kg/CARTON	QTY/CARTON	CARTON SIZE

MANUFACTURE DWG			东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD	
DECIMALS:	ANGLES:	PAR	MCS-302S-C1	
X.:±0.20	X'.:±2'	DWN		
X.X:±0.15	.X':±1'	CHKD		
X.XX:±0.10		APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A